



OIF To Demonstrate 100G Multi-Vendor Interoperability at ECOC 2014
Live Tests Highlight 100G Links and Thermal Optimization

Fremont, Calif. – September 3, 2014 – The Optical Internetworking Forum, operating with the theme of “OIF Interoperability 2014 - Accelerating Momentum on the Road to Next-Generation Architectures” has completed a multi-vendor interoperability demonstration highlighting the expansion of 100G component availability to smaller form factors by testing live traffic over media including optical fiber, copper cables and backplanes. The event marks the OIF's fifth demonstration of 4 x 25Gb/s (100Gb/s) channels and includes nine different demo scenarios featuring 11 different participating companies. The demonstrations will be on display at ECOC in Cannes, France during September 22-24.

The OIF members participating in the demos include Amphenol, Finisar, Fujitsu Optical Components, Inphi, JDSU, Molex, MoSys, Semtech, TE Connectivity, Xilinx and Yamaichi Electronics along with Agilent Technologies and Tektronix providing testing equipment. A white paper will be available during the ECOC demonstration at http://www.oiforum.com/public/OIF_Interoperability_2014.html.

“OIF members continue to lead the industry in developing agreements that enable an interoperable ecosystem of hardware based on 25 to 28Gb/s electrical and optical channels,” said Ed Frlan of Semtech and the OIF Physical and Link Layer Interoperability Working Group chair. “The demonstrations at ECOC validate the work that has been completed within the OIF and the next generation work that is in-process.”

Interoperable demonstrations at ECOC include:

- CFP4 optical modules from multiple suppliers with CEI-28G-VSR electrical channels interoperating over a range of single mode fiber lengths,

- A CFP4 active copper cable assembly operating with CEI-28G-VSR links with multiple ASIC suppliers,
- Testing and validation of chip to module “VSR channels” with compliance boards per CEI-28G-VSR,
- Interoperation of various QSFP28 direct attach copper cables (DAC) from multiple vendors over CEI-25G-LR channels,
- Three different connector supplier’s electrical backplane connectors showing CEI-25G-LR operation with multiple SerDes suppliers,
- A demonstration of the effects of variations in surface condition on thermal performance with the 400G CDFP Style 2 pluggable module per the on-going OIF thermal interface development project.

Speaking Sessions at ECOC

OIF leaders will speak at ECOC on software-defined networking (SDN):

09/21/14 - 2:00pm - 5:30pm

Workshop: NFV/SDN - What It Means for Optical Networking

Chairs and Organizers: Vishnu Shukla, OIF President, Verizon; Hans-Martin Foisel, OIF Board Member and Carrier Working Group Chair, Deutsche Telekom

09/24/14 - 10:20am - 10:50am

Market Focus Theater

Topic: Transport SDN at OIF – Assuring a Seamless Evolution to Interoperable Transport Networks of the Future

Speaker: Vishnu Shukla, OIF President, Verizon

About the OIF

Launched in 1998, the OIF is the first industry group to unite representatives from data and optical networking disciplines, including many of the world's leading carriers, component manufacturers and system vendors. The OIF promotes the development and deployment of interoperable networking solutions and services through the creation of Implementation Agreements (IAs) for optical, interconnect, network processing, component and networking systems technologies. The OIF actively supports and extends the work of standards bodies and industry forums with the goal of promoting worldwide compatibility of optical internetworking products. Information on the OIF can be found at <http://www.oiforum.com>.

